

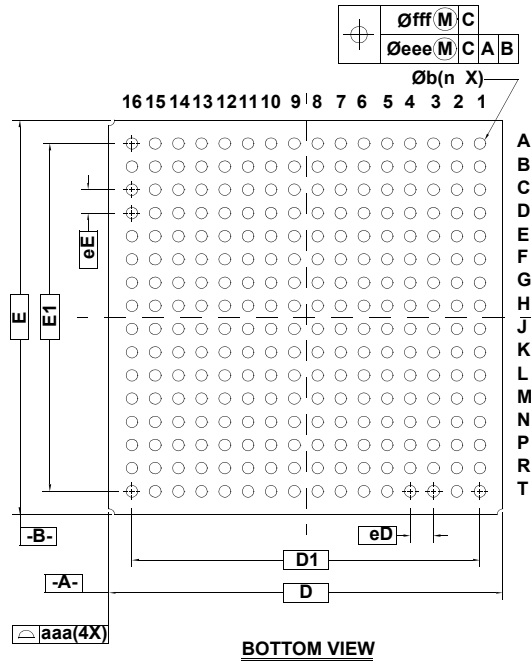
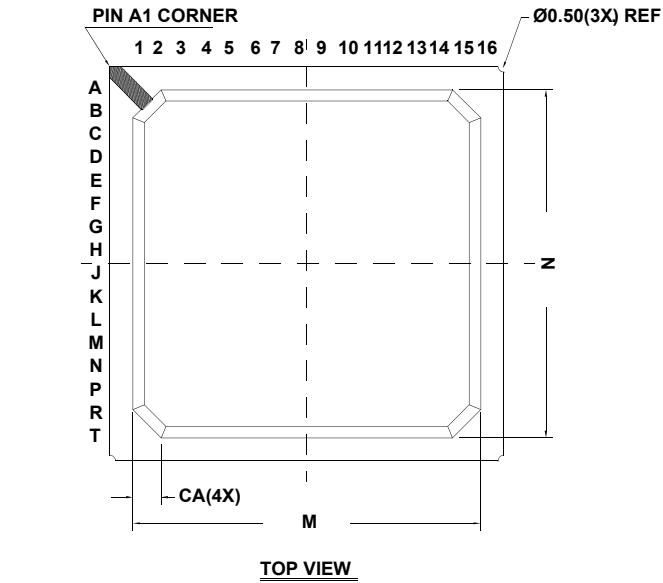
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

### V256.17x17C

256 PLASTIC BALL GRID ARRAY PACKAGE (PBGA)

Rev 0, 6/13



		SYMBOL	COMMON DIMENSIONS
Package			PBGA
Body Size	X	D	17.00
	Y	E	17.00
Ball Pitch	X	eD	1.000
	Y	eE	1.000
Total Thickness		A	1.810 ±0.190
Mold Thickness		A3	0.850 Ref.
Substrate Thickness		A2	0.560 Ref.
Ball Diameter			0.500
Stand Off		A1	0.300 ~ 0.500
Ball Width		b	0.400 ~ 0.600
Mold Area	X	M	15.000
	Y	N	15.000
Chamfer		CA	1.215*45°.
Package Edge Tolerance		aaa	0.200
Substrate Flatness		bbb	0.250
Mold Flatness		ccc	0.350
Coplanarity		ddd	0.150
Ball Offset (Package)		eee	0.250
Ball Offset (Ball)		fff	0.100
Ball Count		n	256
Edge Ball Center to Center	X	D1	15.000
	Y	E1	15.000

